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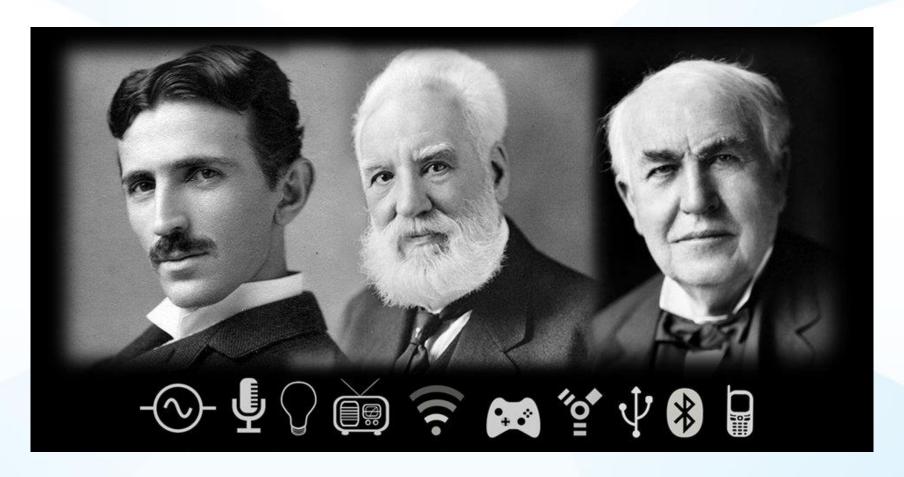
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1884: Where we came from





About the IEEE

- World's largest technical membership association with more than 430,000 members in over 160 countries
- Not for profit organization "Advancing Technology For Humanity"
- Four Core areas of activity
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 - Conferences organizer
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- Bell Labs Technical Journal (BLTJ) back to 1922
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- 14 of the top 15 journals in Telecommunications
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- **3 of the top 5** journals in Automation & Control Systems
- **3 of the top 5** journals in Artificial Intelligence
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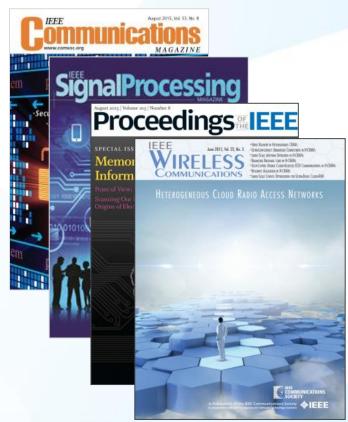


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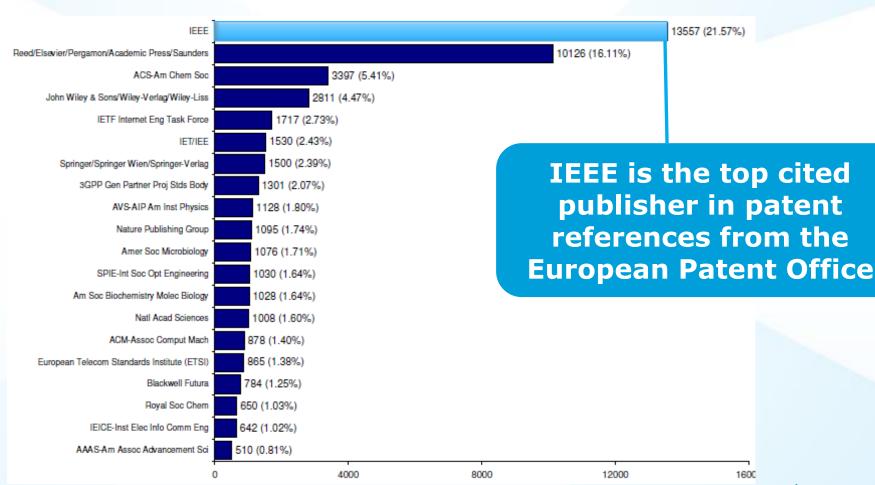


Source: 1790 Analytics LLC 2015. Based on number of references to papers/standards/conferences from 1997-2014



IEEE Leads European Patent Citations

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Source: 1790 Analytics LLC 2012, , Science References from 1997-2011

Technology areas where patents cite IEEE most

Battery

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Computer software

Information storage

Measuring, testing, and control

Medical devices

Nuclear and X-ray

Optics

Power systems

Robotics

Semiconductors

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IEEE Systems, Man, and Cybernetics Society

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IEEE Vehicular Technology Society



IEEE covers all areas of technology

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MACHINE LEARNING BIG DATA

OPTICS RENEWABLE ENERGY

SEMICONDUCTORS SMART GRID

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- Examples of IEEE publications:
 - IEEE Pulse
 - IEEE Trans. on Biomedical Engineering
 - IEEE Reviews on Biomedical Engineering
 - IEEE Trans. on Neural Systems and Rehabilitation Engineering
 - IEEE Trans. on Information Technology in Biomedicine
 - IEEE Trans. on Medical Imaging
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 - IEEE Trans. on Biomedical Circuits and Systems
 - IEEE Trans. on NanoBioscience
 - IEEE Trans. on Autonomous Mental Development.



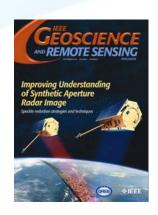






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- Examples of IEEE publications:
 - IEEE Trans. on Geoscience & Remote Sensing
 - IEEE Geoscience & Remote Sensing Magazine
 - IEEE Geoscience & Remote Sensing Letters
 - IEEE International Symposium Geoscience and Remote Sensing (IGARSS)
 - IEEE Petroleum and Chemical Industry Technical Conference (PCIC)





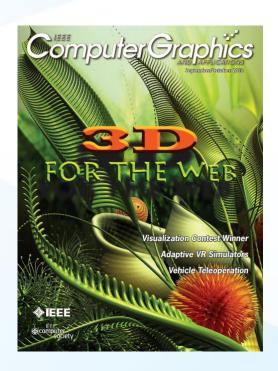
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 (#1 most cited journal in Engineering Manufacturing)
 - IEEE Transactions on Components, Packaging and Manufacturing Technology
 - IEEE Transactions on Semiconductor Manufacturing
 - IEEE Transactions on Automation Science and Engineering
 - IEEE Robotics & Automation Magazine
 - IEEE International Symposium on Assembly and Manufacturing
 - International Conference on Digital Manufacturing and Automation
 - e-Manufacturing & Design Collaboration Symposium Electronics Manufacturing Technology Symposium
 - International Conference on System Science, Engineering Design and Manufacturing Informatization



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 - IEEE Computer Graphics
 - IEEE Trans. On Visualization & Computer Graphics
 - International Conference on Computer-Aided Design
 & Computer Graphics
 - International Conference on Computer Graphics,
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Game Design

- IEEE Xplore covers the design of video games, mathematical games, human-computer interactions in games, and games involving physical objects.
- Topics include game production, computational intelligence, artificial intelligence, simulations, and more
- Examples of IEEE Xplore publications:
 - IEEE Trans. On Computational Intelligence and AI in Games
 - Symposium on Computational Intelligence in Games
 - International Conference on Computer Games
 - International Workshop on Digital Game and Intelligent Toy Enhanced Learning
 - International Symposium on Haptic, Audio, Visual Environments and Games

Computational Intelligence in Games 2014 August 26 – 29, Park Inn Hotel, Dortmund, Germany





Healthcare: telemedicine, electronic medical records, patient-specific healthcare, cloud computing in the medical field, patient monitoring systems, informatics, and more

IEEE TRANSACTIONS ON INFORMATION TECHNOLOGY IN BIOMEDICINE, VOl. 16, NO. 2, MARCH 2012

185

Emerging Technologies for Patient-Specific Healthcare

I. Introduction

ATIENT-SPECIFIC healthcare is a research field that has recently garnered much more attention due to the benefits of better services provided to patients and a reduction of healthcare costs. A series of emerging technologies [1] aim to emphasize the provision of personalized healthcare services to patients [2]–[5]. These include the following.

- Pattern recognition methods for signal pattern classification toward the prediction and diagnosis of diseases.
- Body sensor networks.
- Algorithms for the analysis of patient-specific physiological signals.
- Ontologies and context-based electronic health records (EHRs).
- 5) Methodologies for the internation of clinical in the and

intranuclear spike activity recorded from Parkinson's disease patients.

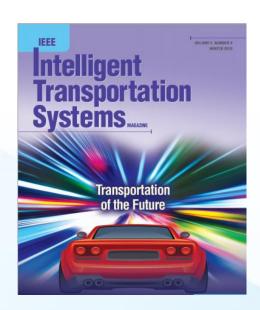
A new Neural Sensing Healthcare System for 3D Vision Technology, NeuroGlasses, is presented in [7]. NeuroGlasses is a nonintrusive, wearable physiological signal monitoring system to facilitate health analysis and diagnosis of 3-D video watchers. The NeuroGlasses system acquires health-related signals by physiological sensors and provides feedback of health-related features. The system employs signal-specific reconstruction and features extraction to compensate the distortion of signals caused by the variation of sensor placement. Through an on-campus pilot study, the experimental results show that NeuroGlasses system can effectively provide physiological information.

In the authors explore how the rhythmogram can be used



Transportation: intelligent transportation systems, logistics, supply chain management, and more

- Related IEEE Journals & Conferences:
 - IEEE Trans. on Intelligent Transportation
 Systems
 - IEEE Intelligent Transportation Systems
 Magazine
 - IEEE Trans. on Automation Science and Engineering
 - IEEE International Conference on Automation and Logistics





Entertainment: computer graphics, animation, 3D, digital motion pictures, laser projectors, and more

Bringing Physical Characters to Life

Akhil J. Madhani Walt Disney Imagineering R&D

Ray Tracing for the Movie 'Cars'

Per H. Christensen*

Julian Fong

David M. Laur

Dana Batali

Pixar Animation Studios

ABSTRACT

Abstract

At Disney, we are s to present these ch entertainment robot Disney in attraction: In this talk, I hope Disney. In particula distilled from Disne As examples of cha I discuss two newer the Disney theme

developed in conjur

and has made appe

This paper describes how we extended Pixar's RenderMan renderer with ray tracing abilities. In order to ray trace highly complex scenes we use multiresolution geometry and texture caches, and use ray differentials to determine the appropriate resolution. With this method we are able to efficiently ray trace scenes with much more geometry and texture data than there is main memory. Moviequality rendering of scenes of such complexity had only previously been possible with pure scanline rendering algorithms. Adding ray

texture cache keeps recently accessed texture tiles ready for fast access. This combination of ray differentials and caching makes ray tracing of very complex scenes feasible.

This paper first gives a more detailed motivation for the use of ray tracing in 'Cars', and lists the harsh rendering requirements in the movie industry. It then gives an overview of how the REYES algorithm deals with complex scenes and goes on to explain our work on efficient ray tracing of equally complex scenes. An explanation of our hybrid rendering approach, combining REYES with ray tracing, follows. Finally, was measure the efficiency of our method on a





Apparel Design: e-textiles, smart fabrics, intelligent clothing, wearable computing, and more



Smart Textiles: From Niche to Mainstream

Jingyuan Cheng, Paul Lukowicz, Niels Henze, Albrecht Schmidt, Oliver Amft, Giovanni A. Salvatore, and Gerhard Tröster

s with many new technologies, smart clothing and textile electronics currently suffer from the chicken-and-egg problem—that is, for the devices to be widely deployed, the price must come down, but for the price to come down, the devices must be mass-produced (problem ely deployed).

between the various people creating the fabric, garments, electronics platforms, and apps (see Figure 1).

The solution to the chicken-and-egg problem must incorporate all steps from garment production through to wearable sensing apps. With approariate abstraction as shown in process should essentially remain series of cutting and sewing steps, possibly including the integration of different materials. Designers could apply this process to the sensing layer, as well, to align the sensors with the garment and with targeted application benains. However, three aguirement



New IEEE Journals Planned for 2017

In 2017, IEEE will introduce six new journals that will be available for subscription:

- IEEE Communications Standards Magazine
- IEEE Journal of Electromagnetics, RF and Microwaves in Medicine and Biology
- IEEE Transactions on Emerging Topics in Computational Intelligence
- IEEE Transactions on Green Communications and Networking
- IEEE Transactions on Radiation and Plasma Medical Sciences
- IEEE Journal of Radio Frequency Identification
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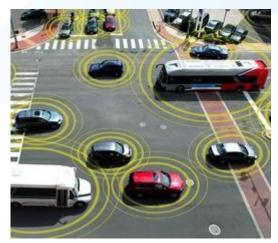




New IEEE Journals Coming in 2016

In 2016, IEEE will introduce four new journals that will be available for subscription:

- IEEE Transactions on **Intelligent Vehicles**
- IEEE Journal on Multiscale and Multiphysics Computational Techniques
- IEEE Robotics and Automation Letters
- IEEE Transactions on Sustainable Computing





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New IEEE Journals from 2015

- IEEE Trans. on **Big Data**
- IEEE Trans. on Transportation Electrification
- IEEE Trans. on Cognitive Communications and Networking
- IEEE Trans. on Computational Imaging
- IEEE Trans. on Molecular, Biological, and Multi-Scale Communications
- IEEE Trans. on Multi-Scale Computing **Systems**
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A sampling of some of the new conferences added in 2015

- Big Data Software Engineering (BIGDSE), 2015 IEEE/ACM 1st International Workshop on
- Computational Electromagnetics (ICCEM), 2015 IEEE International Conference on
- DC Microgrids (ICDCM), 2015 IEEE First International Conference on
- Electromagnetic Compatibility and Signal Integrity, 2015 IEEE Symposium on
- Identity, Security and Behavior Analysis (ISBA), 2015 IEEE International Conference on
- Industrial Engineering and Operations Management (IEOM), 2015 International Conference on
- Microwaves for Intelligent Mobility (ICMIM), 2015 IEEE MTT-S International Conference on

- Multimedia Big Data (BigMM), 2015 IEEE International Conference on
- Networking Systems and Security (NSysS), 2015 International Conference on
- Sampling Theory and Applications (SampTA), 2015 International Conference on
- Signal Processing, Informatics, Communication and Energy Systems (SPICES), 2015 IEEE International Conference on
- Smart Cities Conference (ISC2), 2015 IEEE First International



Examples of New IEEE Conferences in 2014



- Internet of Things (WF-IoT), 2014 IEEE World Forum on
- Humanitarian Technology Conference, (IHTC), 2014 IEEE Canada International
- Aerospace Electronics and Remote Sensing Technology (ICARES), 2014 IEEE International Conference on
- Antenna Measurements & Applications (CAMA), 2014 IEEE Conference on
- Consumer Electronics, Taiwan (ICCE-TW), 2014 IEEE International Conference on
- **Energy Conversion** (CENCON), 2014 IEEE Conference on
- Ethics in Science, Technology and Engineering, 2014 IEEE International Symposium on

- Transportation Electrification Asia-Pacific (ITEC Asia-Pacific), 2014 IEEE Conference and Expo
- **Intelligent Energy** and Power Systems (IEPS), 2014 IEEE International Conference on
- **Quantum Optics Workshop** (QOW), 2014
- Sensor Systems for a Changing Ocean (SSCO), 2014 IEEE
- Wireless and Mobile, 2014 IEEE Asia Pacific Conference on
- Industrial Engineering and Information Technology (IEIT), 2014 International Conference on
- Guidance, Navigation and Control Conference (CGNCC), 2014 IEEE Chinese



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IEEE 81-2012™—IEEE Guide for Measuring Earth Resistivity, Ground Impedance, and Earth Surface Potentials of a Grounding System

2012 National Electrical Safety Code® (NESC®)—Sets the ground rules for practical safeguarding of persons during the installation, operation, or maintenance of electric supply and communications lines and associated equipment.

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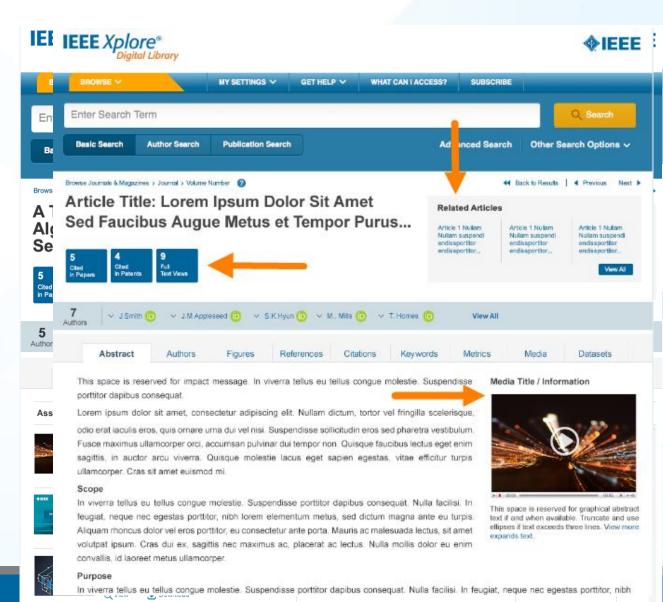
IEEE 80™—IEEE Guide for Safety in AC Substation Grounding

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Enhancing the User Experience: Redesign of Full-Text HTML Articles

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NEW! Full-Text HTML for Standards IEEE Xplore* IEEE Xplore*

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- Search within a Standard
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What are standards?

- Standards are published documents that establish specifications and procedures designed to ensure the reliability of the materials, products, methods, and/or services people use every day.
- Standards form the fundamental building blocks for product development by establishing consistent protocols that can be universally understood and adopted
 - Standards establish compatibility, interconnectivity, interoperability, simplify product development, and speed time-to-market
- Standards make it easier to understand and compare competing products.
- As standards are globally adopted and applied in many markets, they also help with international trade



Types of IEEE standards

- Standards: Documents with mandatory requirements.
- Recommended Practices: Documents in which procedures and positions preferred by the IEEE are presented.
- Guides: Documents in which alternative approaches to good practice are suggested but no clear-cut recommendations are made.
- Trial-Use Documents: Publications in effect for not more than two years.
 - Can be any of the categories of standards publications listed above.





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States of Activity of IEEE standards

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 standards
 (e.g., drafts).

Active

 Approved standards that have not been transferred to inactive status (e.g., active standards and revisions).

Inactive

• Standards that are no longer being reviewed or assessed for accuracy, relevance to current practices or further applications (e.g., withdrawn standards).



IEEE Standards Development

IEEE standards development process may result in one or more of the following documents:

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- Corrigendum: Document that only corrects editorial errors, technical errors, or ambiguities in an existing IEEE standard. A corrigendum does not introduce new material.
- **Erratum:** Document that contains only grammatical corrections to, or corrections of errors introduced during the publishing process of, an existing IEEE standard.

Who participates in standards development?

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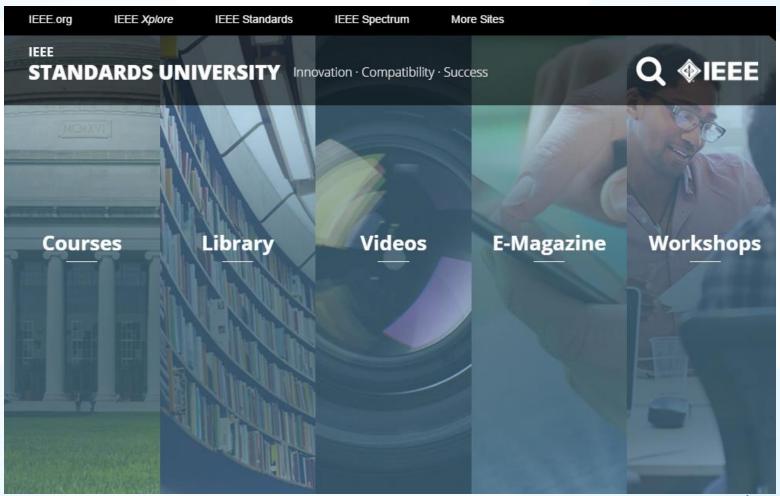
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CON

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- Innovative phased array antennas based on non-regular lattices and overlapped subarrays [call for papers]
- Special Issue on Manipulation, Manufacturing and Measurement on the Nanoscale









Aims & Scope

The theory, design and application of Control Systems. It shall encompass components, and the integration of these components, as are necessary for the construction of such systems. The word 'systems' as used herein shall be interpreted to include physical, biological, organizational and other entities and combinations thereof, which can be represented through a mathematical symbolism. The Field of Interest: shall include scientific, technical, industrial or other activities that contribute to this field, or utilize the techniques or products of this field, subject, as the art develops, to additions, subtractions, or other modifications directed or approved by the IEEE Technical Activities Board.

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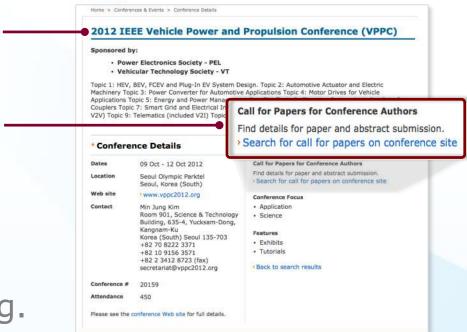


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Conference Name ▲ ▼	Conference Date ▲ ▼	Location ▲ ▼
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2018 IEEE Frontiers in Education Conference (FIE) Abstract submission deadline: 05 Feb 2018 Full Paper Submission deadline: 23 Apr 2018 Final submission deadline: 09 Jul 2018 Notification of acceptance date: 21 May 2018	03 Oct - 06 Oct 2018	TBD TBD San Jose, CA, USA
2018 IEEE World Congress on Computational Intelligence (WCCI) Full Paper Submission deadline: 01 Feb 2018 Final submission deadline: 01 May 2018 Notification of acceptance date: 01 Apr 2018	08 Jul - 13 Jul 2018	Windsor Barra Convention Centre Rua Martinho de Mesquita Barra da Tijuca Rio de Janeiro, Brazil
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2018 IEEE Symposium on Security and Privacy (SP) Full Paper Submission deadline: 16 Nov 2017 Final submission deadline: 31 Mar 2018	20 May - 24 May 2018	Hyatt Regency San Francisco 5 Embarcadero Center San Francisco CA USA

IEEE

San Francisco, CA, USA

Structure



Paper Structure

Elements of a manuscript

Title

Abstract

Keywords

Introduction

Methodology

Results/Discussions/Findings

Conclusion

References





Paper Structure Title

An effective title should...

- •Answer the reader's question: "Is this article relevant to me?"
- •Grab the reader's attention
- •Describe the content of a paper using the fewest possible words
 - Is crisp, concise
 - Uses keywords
 - Avoids jargon





Paper Structure

Good vs. Bad Title

A Human Expert-based Approach to Electrical Peak Demand Management

VS

A better approach of managing environmental and energy sustainability via a study of different methods of electric load forecasting



Paper Structure

Good vs. Better Title

An Investigation into the Effects of Residential Air-Conditioning Maintenance in Reducing the Demand for Electrical Energy

VS

"Role of Air-Conditioning Maintenance on Electric Power Demand"



Paper Structure Abstract

Why you did A "stand alone" condensed version of the article No more than 250 words; What you did written in the past tense Uses keywords How the results and index terms were useful, important & move the field forward Why they're useful & important & move the field forward



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The abstract must be a **concise yet comprehensive reflection of what is in your article**. In particular, the abstract must be as follows.

- 1) Self-contained, without abbreviations, footnotes, or references; it should be a **microcosm of the full article**
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- 3) Written as **one paragraph**, and should **not contain** displayed **mathematical equations or tabular material**.
- 4) Should include **three or four different keywords or phrases**, as this will help readers to find it. It is important to avoid over-repetition of such phrases as this can result in a page being rejected by search engines.
- 5) Ensure that your abstract **reads well and is grammatically correct**.



Paper Structure

Good vs. Bad Abstract

The objective of this paper was to propose a human expert-based approach to electrical peak demand management. The proposed approach helped to allocate demand curtailments (MW) among distribution substations (DS) or feeders in an electric utility service area based on requirements of the central load dispatch center. Demand curtailment allocation was quantified taking into account demand response (DR) potential and load curtailment priority of each DS, which can be determined using DS loading level, capacity of each DS, customer types (residential/commercial) and load categories (deployable, interruptible or critical). Analytic Hierarchy Process (AHP) was used to model a complex decision-making process according to both expert inputs and objective parameters. Simulation case studies were conducted to demonstrate how the proposed approach can be implemented to perform DR using real-world data from an electric utility. Simulation results demonstrated that the proposed approach is capable of achieving realistic demand curtailment allocations among different DSs to meet the peak load reduction requirements at the utility level.

Vs

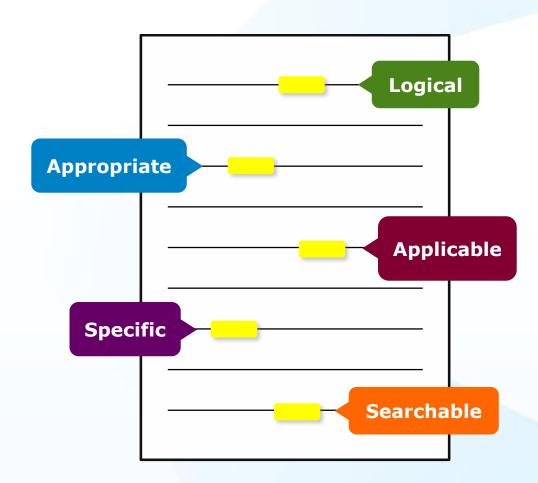
This paper presents and assesses a framework for an engineering capstone design program. We explain how student preparation, project selection, and instructor mentorship are the three key elements that must be addressed before the capstone experience is ready for the students. Next, we describe a way to administer and execute the capstone design experience including design workshops and lead engineers. We describe the importance in assessing the capstone design experience and report recent assessment results of our framework. We comment specifically on what students thought were the most important aspects of their experience in engineering capstone design and provide quantitative insight into what parts of the framework are most important.

First person, present tense
No actual results, only describes the organization of the paper



Paper Structure Keywords

Use in the Title and Abstract for enhanced Search Engine Optimization





IEEE Keywords

Bit rate, Decoding, Encoding, Parallel processing, Video coding

Authors Keywords

High Efficiency Video Coding (HEVC), parallel programming, video coding

INSPEC: Controlled Indexing

parallel processing, video coding

INSPEC: Non-Controlled Indexing

12-core system, H.264-advanced video coding, HEVC parallelization approaches, OWF, WPP, frequency 3.33 GHz, high efficiency video coding, overlapped wavefront, parallel efficiency, parallel friendliness, parallel scalability, parallelization proposals, tiles, wavefront parallel processing



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Paper Structure Introduction

- A description of the problem you researched
- It should move step by step through, should be written in present tense:

Generally known information about the topic

Prior studies'
historical
context to your
research

Your hypothesis and an overview of the results

How the article is organized

- The introduction should <u>not be</u>
 - Too broad or vague
 - More then 2 pages



Paper Structure Methodology

- Problem formulation and the processes used to solve the problem, prove or disprove the hypothesis
- Use illustrations to clarify ideas, support conclusions:

Tables

Present representative data or when exact values are important to show



Figures

Quickly show ideas/conclusions that would require detailed explanations



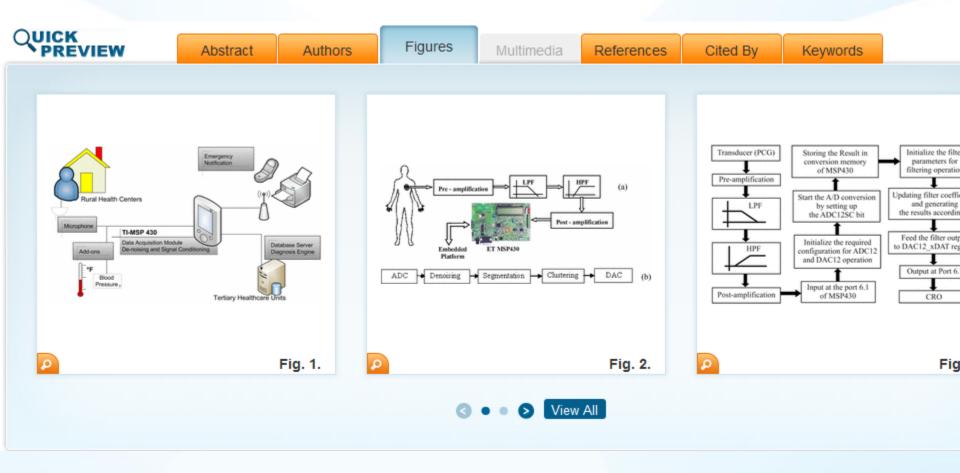
Graphs

Show relationships between data points or trends in data



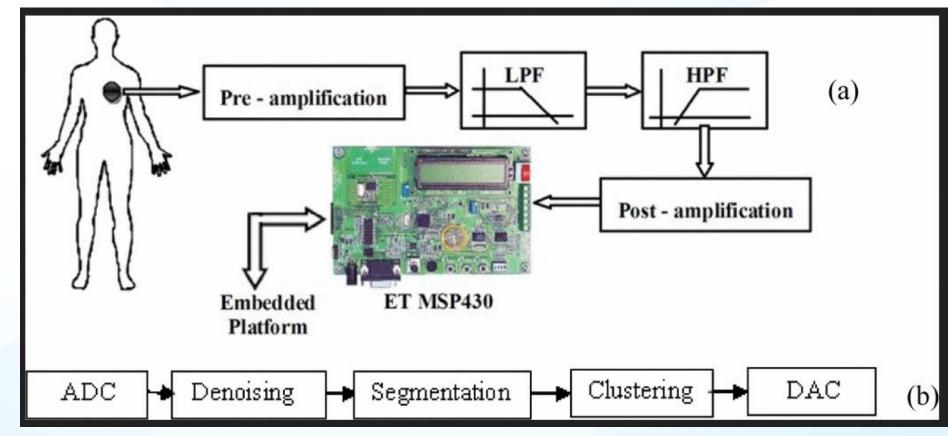


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Equations in TeX Source in HTML version

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```
 $\eqalignno{\{\rm\ HS\}_{\{\rm\ recover\}} \& \|=\| \left(1 - \{E\eft\{x_{\{\rm\ HS\}}^2 \setminus \{rm\ reduct)\} \right} - E\eft\{\{y^2 \setminus \{rn\ right\}\} \right} \right) }
```

and NOISE reduction are computed in terms of percentages (see Table 1)

$$\text{HS}_{\text{recover}} = \left(\frac{1 - E\{x_{\text{HS}}^{2}(n)\} - E\{y^{2}(n)\}}{E\{x_{\text{HS}}^{2}(n)\}}\right) \times 100\%$$

$$\text{NOISE}_{\text{reduction}} = \left(\frac{E\{x_{\text{hs_noi}}^{2}(n)\} - E\{y^{2}(n)\}}{E\{x_{\text{hs_noi}}^{2}(n)\}}\right) \times 100\%$$

$$E\{x_{\text{hs_noi}}^{2}(n)\}$$



Paper Structure Results/discussion

Demonstrate that you solved the problem or made significant advances

Results: Summarized Data

- Should be clear and concise
- Use figures or tables with narrative to illustrate findings

Discussion: Interprets the Results

- Why your research offers a new solution
- Acknowledge any limitations

the SC algorithm over the whole range of w values increase to 3-4 K, except for the TIGR: to database, with an RMSE of 2 K. This last result is explained by the w distribution, which is biased toward low values of w in this database. When only atmospheric profiles with to values lower than S g - cm - 2 are selected, the SC algorithm provides RMS around 1.5 K, with almost equal values of bias and standard deviation, around 1 K in both cases (with a negative bias, thus the SC underestimates the LST). In contrast, when only w values higher than 3 g \cdot cm $^{-2}$ are considered, the SC algorithm provides RMSEs higher than 5 K. In these cases, it is preferable to calculate the atmospheric functions of the SC algorithm directly from (3) rather than approximating them by a polynomial fit approach as given by (4).

V. DISCUSSION AND CONCLUSION The two Landsat-S TIR bands allow the intercomparison

of two LST retrieval methods based on different physical such as the SC (only one TIR band required) fams (two TIR bands required). Direct inversion e transfer equation, which can be considered orithm, is assumed to be a "ground-truth" **Discussion** and L_d) is accurate enough. The SC algoin this letter is a continuation of the previous SC veloped for Landsat-4 and Landsat-5 TM sensors, ne ETM+ sensor on board the Landsat-7 platform [9], and it could be used to generate consistent LST products from the historical Landsat data using a single algorithm. An advantage of the SC algorithm is that, apart from surface emissivity, only water vapor content is required as input. However, it is expected that errors on LST become unacceptable for high water upper contents (e.g., > 3 g \cdot cm⁻²). This problem can be purify solved by computing the atmospheric functions directly from τ , L_{∞} , and $L_{\mathcal{L}}$ values [see (5)], or also by including air temperature as input [15]. A main advantage of the SW algorithm is that it performs well over global conditions and, thus, a wide range of water vapor values; and that it only requires water vapor as input (apart from surface emissivity at the two TIR bands). However, the SW algorithm can be only applied to the new Landant-S TIRS data, since previous TM/ETM sensors only had one TIR band.

The LST algorithms presented in this letter were tested with simulated data sets obtained for a variety of global atmospheric conditions and surface emissivities. The results showed RMSE values of typically less than 1.5 K, although for the SC algorithm, this accuracy is only achieved for w values below 3 g - cm⁻². Algorithm testing also showed that the SW errors are lower than the SC errors for increasing water vapor, and vice versa, as demonstrated in the simulation study presented in Sobrino and Jiménez-Muñoz [18]. Although an extensive validation exercise from in sits measurements is required to assess the performance of the two LST algorithms, the results obtained for the simulated data, the sensitivity analysis, as well as the previous findings for algorithms with the same mothemotical structure give confidence in the algorithm accuracies

Results

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Paper Structure Conclusion

- Explain what the research has achieved
 - As it relates to the problem stated in the Introduction
 - Revisit the key points in each section
 - Include a summary of the main findings, important conclusions and implications for the field
- Provide benefits and shortcomings of:
 - The solution presented
 - Your research and methodology
- Suggest future areas for research





Paper Structure References

- Support and validate the hypothesis your research proves, disproves or resolves
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 - But use only those that directly support our work
- Ensure proper author attribution
 - Author name, article title, publication name, publisher, year published, volume, chapter and page number
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1538

Properly

cited material

We then have

$$(P_t^{a,+} + P_t^{a,-})^2 - (P_t^{a,+} - P_t^{a,-})^2 + 4P_t^{a,+}P_t^{a,-}$$

 $< (\hat{P}_t^{a,+} - \hat{P}_t^{a,-})^2 + 4\hat{P}_t^{a,+}\hat{P}_t^{a,-}$
 $- (\hat{P}_t^{a,+} + \hat{P}_t^{a,-})^2.$ (32)

Since $P_i^{h,+} - P_i^{h,-} = P_i^{h,+} - P_i^{h,-}$, we then have $P_i^{h,+} < P_i^{h,+}$, and $P_i^{h,-} < P_i^{h,-}$. Because the operational cost is an increasing function of $\{P_i^{h,+}, P_i^{h,-}\}$, we obtain that

$$c_{n/m}(P_t^{s,+}, P_t^{s,-}) < c_{n/m}(\hat{P}_t^{s,+}, \hat{P}_t^{s,-}).$$
 (33)

Therefore the optimal pair $\{P_i^{h,+}, P_i^{h,-}\}$ must satisfy that $P_i^{h,+}P_i^{h,-}=0$, i.e., only one of $P_i^{h,+}, P_i^{h,-}$ can be non-zero.

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His research interests include statistical signal processing, optimization, machine learning, and coresponding with applications to awart grids.



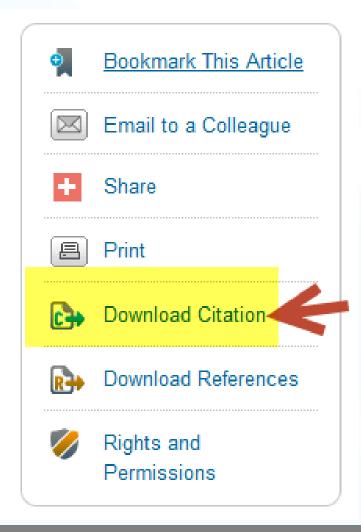
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He is the Eugene and Martin Lohman Professor and Chair of the Preston M. Clesso Department of Electrical and Systems Engineering (1851); at Washington University in St. Louis (WUSTL), St. Louis, MO, USA. Earlier, he was a facely as ember at Talis University and the University of Illinois at Chicago.

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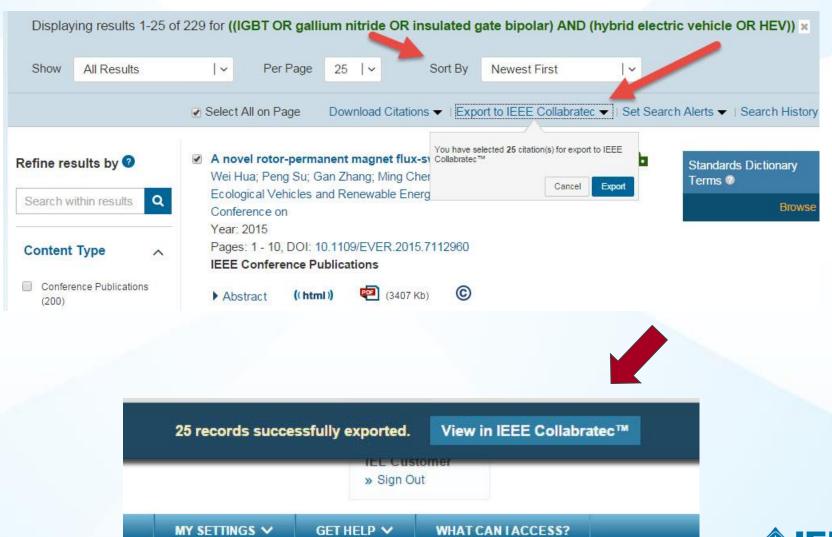
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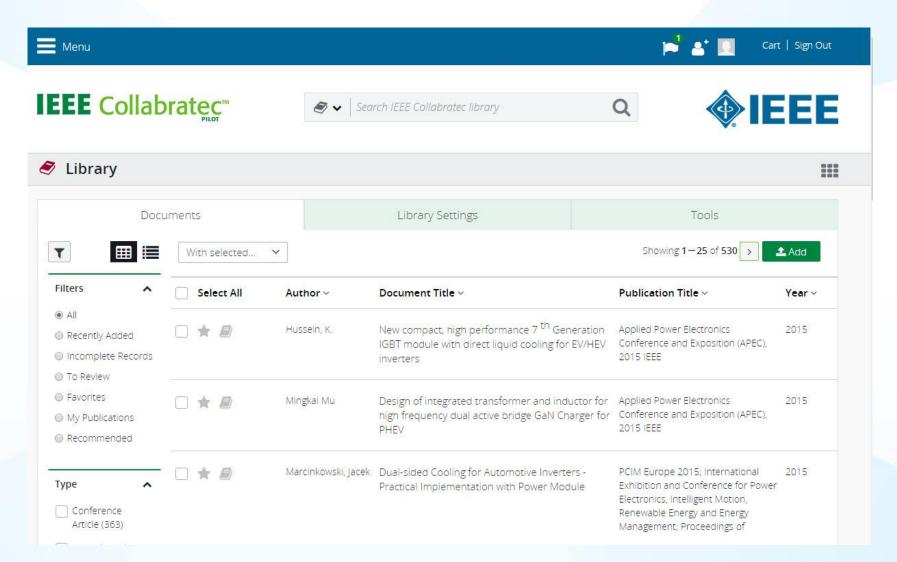


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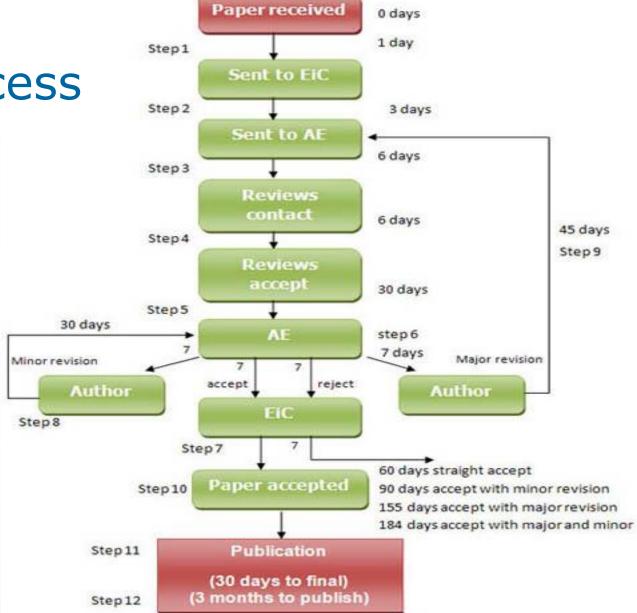
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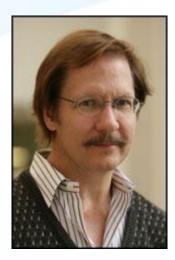
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Preparation of Papers for IEEE TRANSACTIONS and JOURNALS (December 2013)

First A. Author, Fellow, IEEE, Second B. Author, and Third C. Author, Jr., Member, IEEE

Abstract—These instructions give you guidelines for preparing papers for IEEE Transactions and Journals. Use this document as a template if you are using Microsoft Word 6.0 or later. Otherwise, use this document as an instruction set. The electronic file of your paper will be formatted further at IEEE. Paper titles should be written in uppercase and lowercase letters, not all uppercase. Avoid writing long formulas with subscripts in the title; short formulas that identify the elements are fine (e.g., "Nd-Fe-B"). Do not write "(Invited)" in the title. Full names of authors are preferred in the author field, but are not required. Put a paper between suthors' initials. Define all symbols used in the abstract. Do not cite references in the abstract. Do not delete the blank line immediately above the abstract; it sets the footnote at the bottom of this column.

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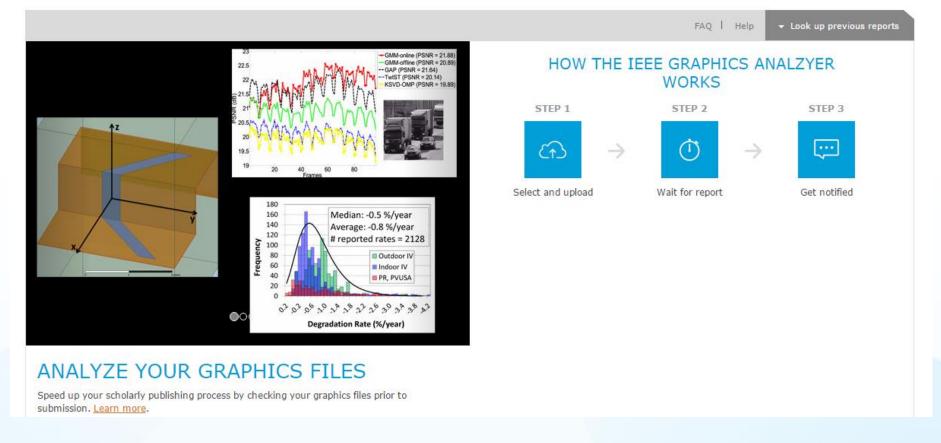
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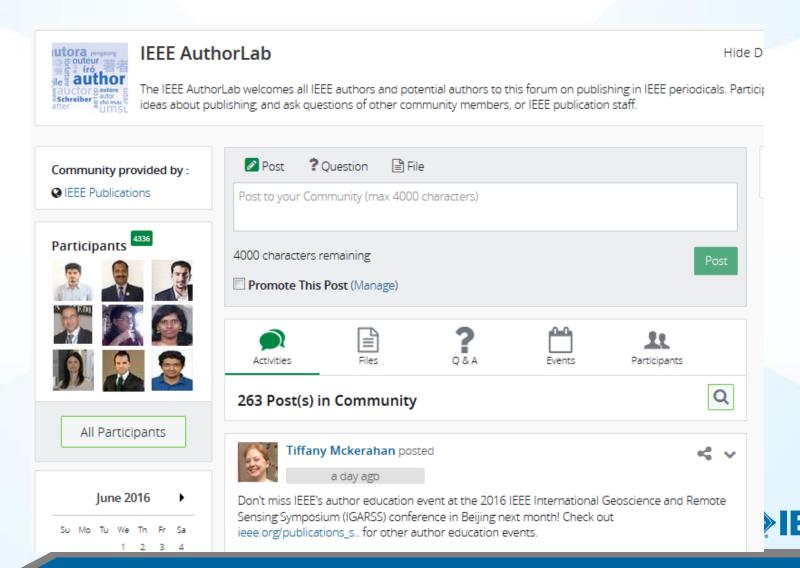
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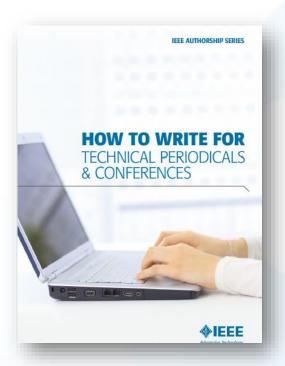
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